

ABSTRACT OF THE DISCLOSURE

A semiconductor chip (15) having a pad (5) covered with a passivation film (7) is prepared, and the passivation film (7) over the pad (5) is selectively removed to expose 5 the pad (5). Next, a polyimide film (11) having an opening (12) for exposing the pad (5) is formed on the passivation film (7). Thereafter, solder bumps (14) are formed on the pad (5), and an underfill resin (17) is filled between an assembly substrate (16) and the semiconductor chip (15) to bond the assembly substrate (16) and semiconductor chip (15) with the solder bumps (14) interposed therebetween.